



Material Content Data Sheet



Sales Product Name		BSP752T		Issued		19. January 2018		
MA#		MA001425980						
Package		PG-DSO-8-24		Weight*		83.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.188	2.63	2.63	26281	26281
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8614	
wire	non noble metal	copper	7440-50-8	29.121	34.97	35.88	349749	358902
	noble metal	gold	7440-57-5	0.355	0.43	0.43	4267	4267
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1168
plastics	plastics	epoxy resin	-	4.474	5.37		53731	
		inorganic material	silicondioxide	60676-86-0	44.057	52.91	58.40	529136
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9774	9774
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7810	7810
glue	plastics	epoxy resin	-	0.130	0.16		1563	
		noble metal	silver	7440-22-4	0.613	0.74	0.90	7368
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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